

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination DIP ET AL.	
		10/647,534	Examiner Julio J. Maldonado	
			Art Unit 2823	Page 1 of 1

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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.